



# Product Change Notification

## 104052 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geography location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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# Product Change Notification

**Change Notification #:** 104052 - 00  
**Change Title:** 100L TQFP FAGD16523100BA,  
FAGD16524100BA, FAGD16556100BA,  
FAGD16556ECLBA, FAGD16557100BA,  
FAGD16557ECLBA, FALXT16596GG,  
FALXT16597GG, PCN 104052-00, FYI,  
Assembly Site and Heat Sink Update  
**Date of Publication:** April 21, 2004

**Type of Change Notification:**  
FYI - (For Your Information)

**Key Characteristics of the Change:**  
Product Material  
Manufacturing Site

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Apr 21, 2004
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## Description of Change to the Customer:

It has come to our attention that the earlier communicated qualification of ASE as assembly site for 100 Lead TQFP packages (refer to PCN 102161-01) did not include accurate information about change in shape of heat sink. As part of the transfer the shape of the heat sink was changed from round 6.6mm diameter to square 8x8mm.

The change in shape of heat sink results in an increased case junction temperature of 10°C for components that have been assembled at the new ASE assembly site. This increase is relative to the junction temperature measured at components from prior assembly site.

First shipments of ASE assembled components were made in August 2002. Components assembled at ASE will comply with the following marking, where the 5th digit represents ASE as assembly site. Components where the 5th digit is either represented as numeric value or a letter other than "Q" have been assembled at "old" assembly site

abcdQefg: "a" (test site), "bcd" (assembly year and work week), "Q" (ASE assembly), "efg" (lot code #)

## Customer Impact of Change and Recommended Action:

Based on reliability data as well as actual results from electrical and thermal validation, Intel has concluded that when operated within the

specifications of the datasheets, components from ASE and components from old assembly site meet reliability specifications and electrical performance as specified in the datasheet.

It is recommended that customers review cooling of their systems to ensure that those systems provide sufficient cooling to accommodate the use of components from the old assembly site as well as components from ASE assembly. This review is optional for customers that have only received components from ASE, or have qualified their systems with this component.

Intel recommends that customers review their PCB traces below, or around, any of the affected components to avoid potential risks of short circuits. This review is optional for customers that have only received components from ASE, or have qualified their systems with this component. (Please refer to details below on how to differentiate "old" assembly components from ASE assembly components)

## Products Affected / Intel Ordering Codes:

### Component Product Table

Pre-Conversion Product Code	Pre-Conversion MM#
FAGD16523100BA	836091
FAGD16524100BA	836092
FAGD16556ECLBA	836093
FAGD16557100BA	834118
FAGD16557ECLBA	836095
FALXT16596GG	837404
FALXT16597GG	837406

## Reference Documents / Attachments:

**Document:**  
PCN102161-01

**Location #:**  
<http://www.intel.com/design/pcn/Networking/D0102161.pdf>

## PCN Revision History:

**Date of Revision:**  
April 21, 2004

**Revision Number:**  
00

**Reason:**  
Originally Published PCN